

WAFER PROCESSING METHOD

ABSTRACT OF THE DISCLOSURE

A wafer processing method includes a wafer providing step of providing the wafer by placing either of a polyolefin sheet or a polyester sheet each of which has a size equal to or larger than that of the wafer, on a flat upper surface of a support table and positioning a front surface of the wafer on an upper surface of the sheet, a sheet thermocompression bonding step of evacuating an enclosing environment in which the wafer is provided through the sheet on the support table, heating the sheet, pressing the wafer to pressure-bond the wafer to the sheet, thereby forming a raised portion by which an outer circumference of the wafer is surrounded, a back surface processing step of processing the back surface of the wafer, and a peeling step of peeling off the wafer from the sheet.

FIGURE 2C